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TMS2019
 148th Annual Meeting & Exhibition

CALL FOR ABSTRACTS

March 10–14, 2019
 San Antonio, Texas, USA

SUBMIT AN ABSTRACT TO:

ADVANCED MATERIALS

High Entropy Alloys VII

This symposium will provide a new venue for presentation of research on the fundamental understanding and theoretical modeling of high-entropy alloy (HEA) processing, microstructures, and mechanical behavior.

In contrast to conventional alloys, which are based upon one principal element, HEAs have multiple principal elements, often five or more. The significantly high entropy of the solid solution stabilizes the solid-solution phases in face-centered-cubic (FCC), body-centered-cubic (BCC), and hexagonal close-packed (HCP) structures against intermetallic compounds. Moreover, carefully-designed HEAs possess tailorable properties that far-surpass their conventional alloys. Such properties in HEAs include high strength, ductility, corrosion resistance, oxidation resistance, fatigue and wear resistance. These properties will undoubtedly make HEAs of interest for use in biomedical, structural, mechanical, and energy applications. Given the novel and exciting nature of HEAs, they are poised for significant growth, not unlike the bulk metallic glass or nanostructured alloy scientific communities, and present a perfect opportunity for a new symposium.

Topics of interest include, but are not limited to:

- Material fabrication and processing, such as homogenization, nanomaterials, and grain-boundary engineering
- Advanced characterization, such as neutron scattering and three-dimensional (3D) atom probe
- Thermodynamics and diffusivity: measurements and modeling
- Mechanical behavior, such as fatigue, creep, and fracture
- Corrosion, physical, magnetic, electric, thermal, coating, and biomedical behavior
- Theoretical modeling and simulation using density functional theory, molecular dynamics, Monte Carlo simulations, phase-field and finite-elements method, and CALPHAD modeling
- Industrial applications

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Abstract Deadline is July 1, 2018.
 Submit online at www.programmaster.org/TMS2019

Questions?
 Contact programming@tms.org